



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: LF5WAEMBGMBW

High Efficiency Red
Blue
Green

Features

- One red, one green and two blue chips in one package.
- Can produce any color in visible spectrum, including white light.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Blue source color devices are made with GaN on SiC Light Emitting Diode.

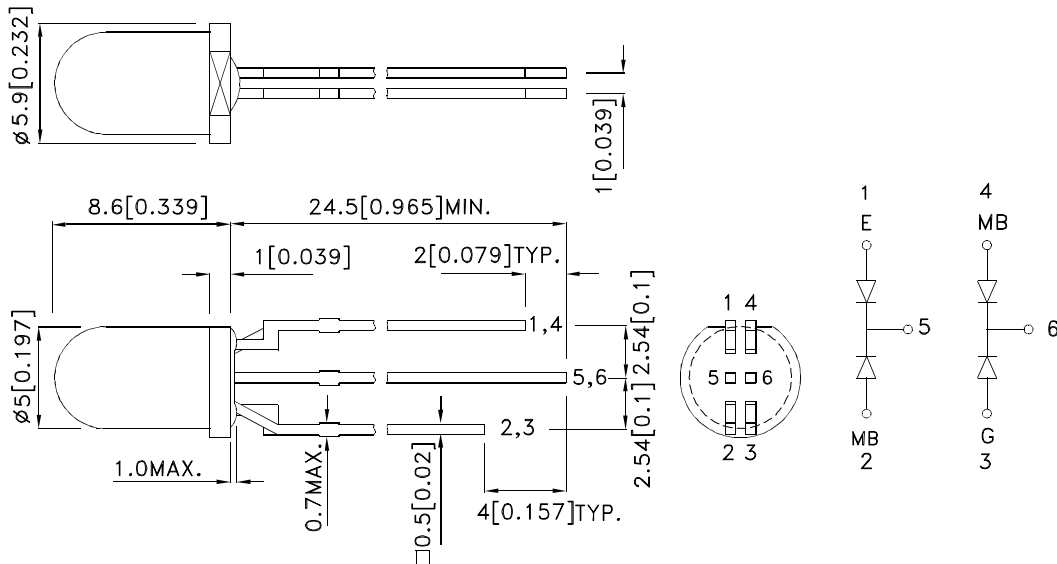
The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25 (0.01)$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
LF5WAEMBGMBW	High Efficiency Red (GaAsP/GaP)	White Diffused	12	30	60°
	Blue (GaN)		10	25	
	Green (GaP)		10	20	
	Blue (GaN)		10	20	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ Luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	High Efficiency Red Blue Green	627 430 565		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	High Efficiency Red Blue Green	625 466 568		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	High Efficiency Red Blue Green	45 60 30		nm	I _F =20mA
C	Capacitance	High Efficiency Red Blue Green	15 100 15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	High Efficiency Red Blue Green	2 3.8 2.2	2.5 4.5 2.5	V	I _F =20mA
I _R	Reverse Current	High Efficiency Red Blue Green		10 10 10	uA	V _R =5V

Notes:

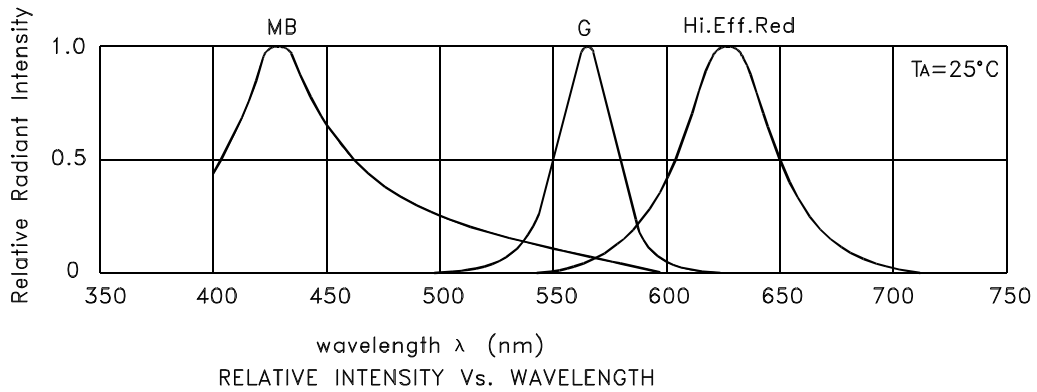
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

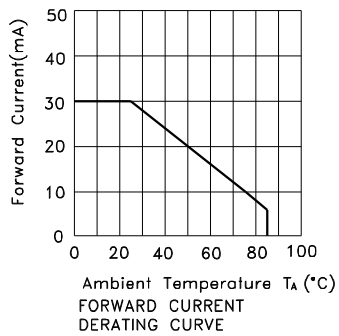
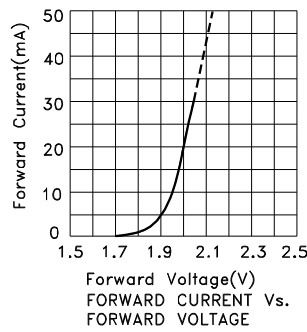
Parameter	High Efficiency Red	Blue	Green	Units
Power dissipation	75	135	62.5	mW
DC Forward Current	30	30	25	mA
Peak Forward Current [1]	160	150	140	mA
Reverse Voltage	5			V
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes:

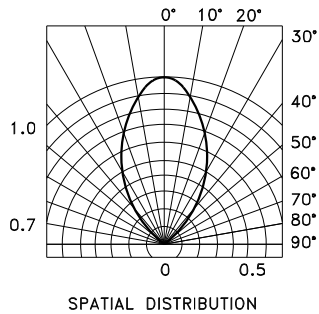
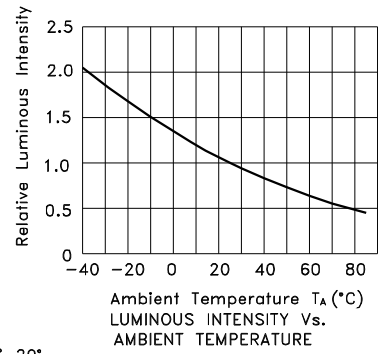
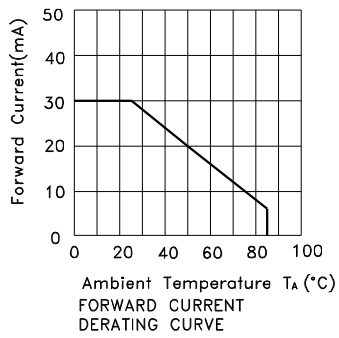
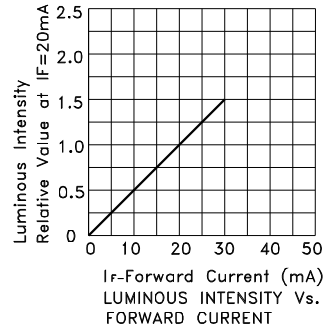
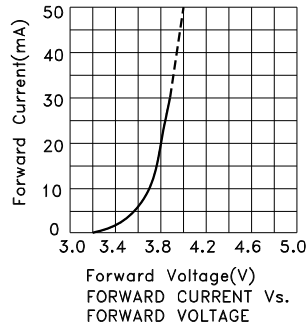
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



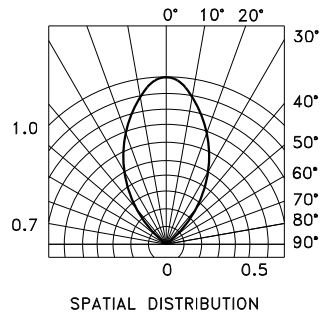
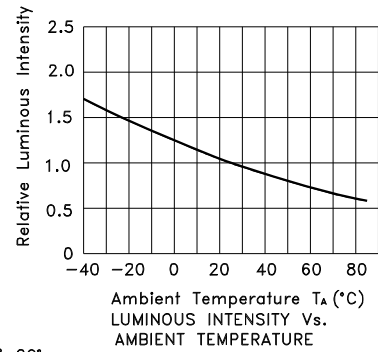
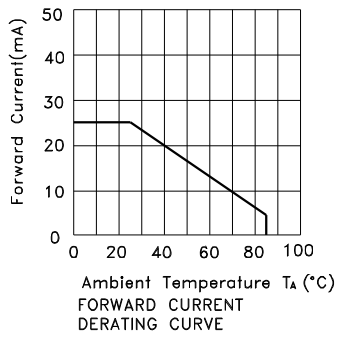
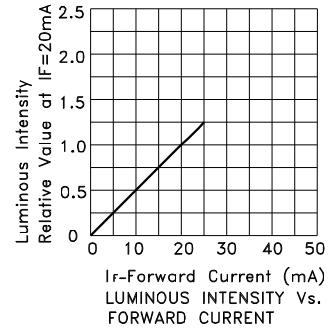
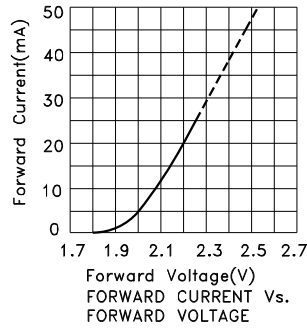
LF5WAEMBGMWBW High Efficiency Red



Blue



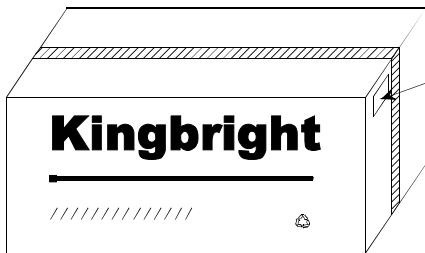
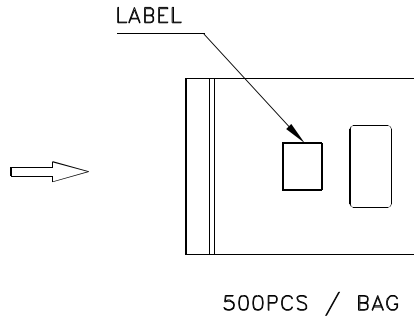
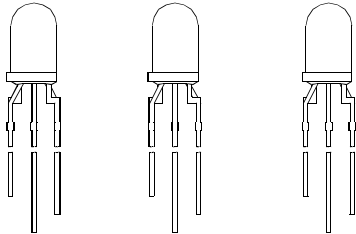
Green



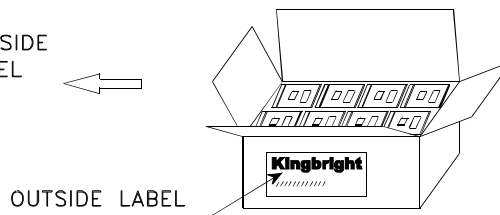
Kingbright

PACKING & LABEL SPECIFICATIONS

LF5WAEMBGBW



OUTSIDE LABEL



OUTSIDE LABEL

<h1>Kingbright</h1>					
P/N0: LF5WAxxx					
QTY: 500 pcs	Q.C.	<table border="1"> <tr> <td style="text-align: center;">Q C</td> </tr> <tr> <td style="text-align: center;">xx xx xxxx</td> </tr> <tr> <td style="text-align: center;">PASSED</td> </tr> </table>	Q C	xx xx xxxx	PASSED
Q C					
xx xx xxxx					
PASSED					
S/N: XXXX					
CODE: XXX					
LOT NO:					
 xxxxxxxxxxxxxxxxxxxxxxxx					
RoHS Compliant					

PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

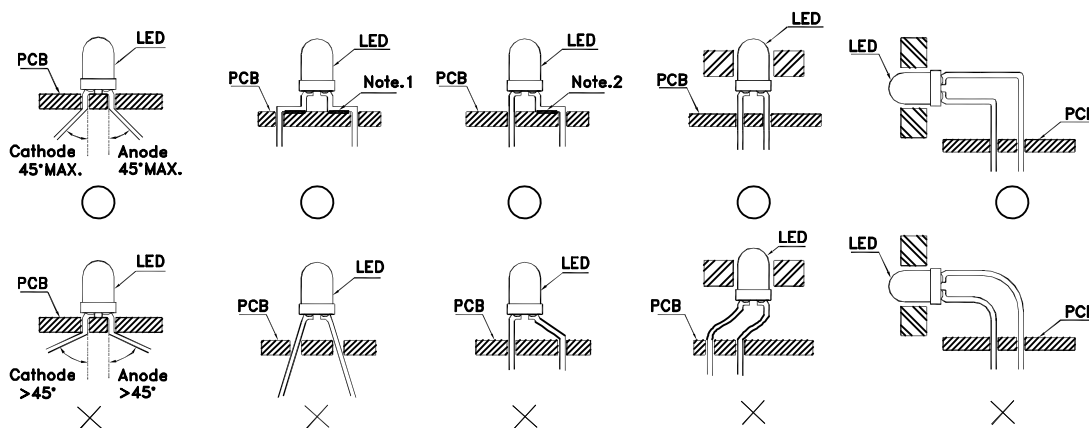


Fig.1

”○” Correct mounting method ”×” Incorrect mounting method

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

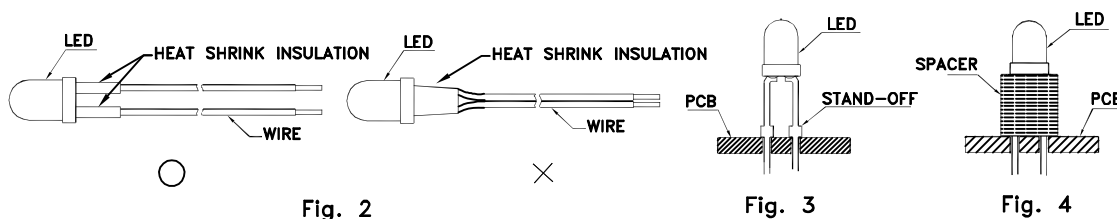


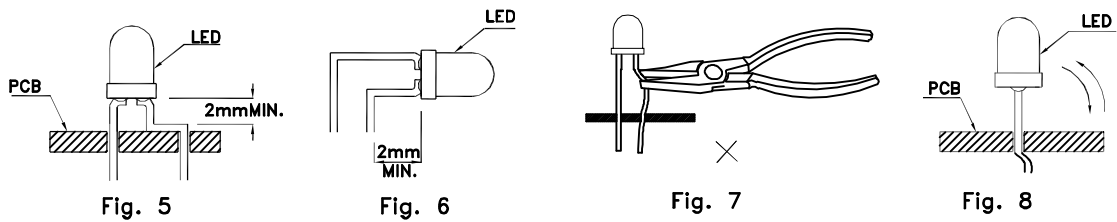
Fig. 2

Fig. 3

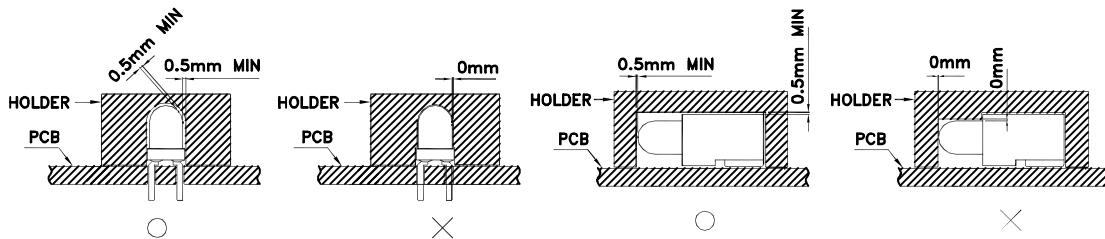
Fig. 4

4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

6. Do not bend the leads more than twice. (Fig. 8)



7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.

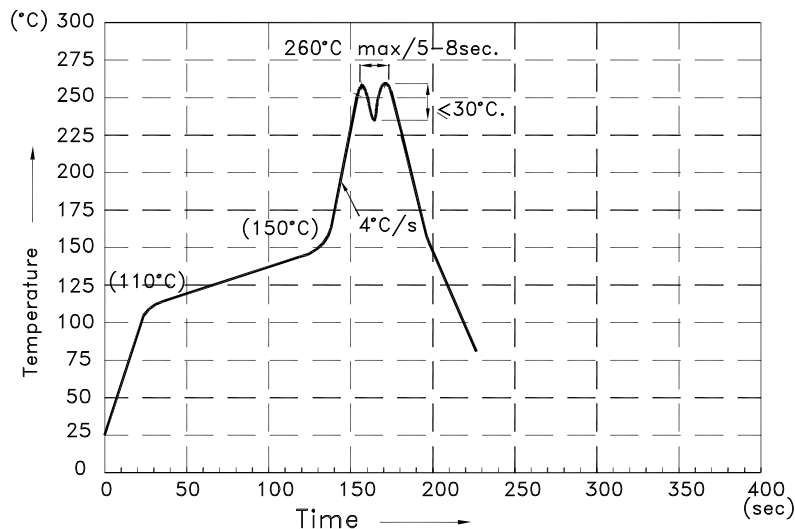


8. The tip of the soldering iron should never touch the lens epoxy.

9. Through-hole LEDs are incompatible with reflow soldering.

10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

11. Recommended Wave Soldering Profile for Kingbright Thru-Hole Products



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.